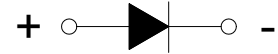
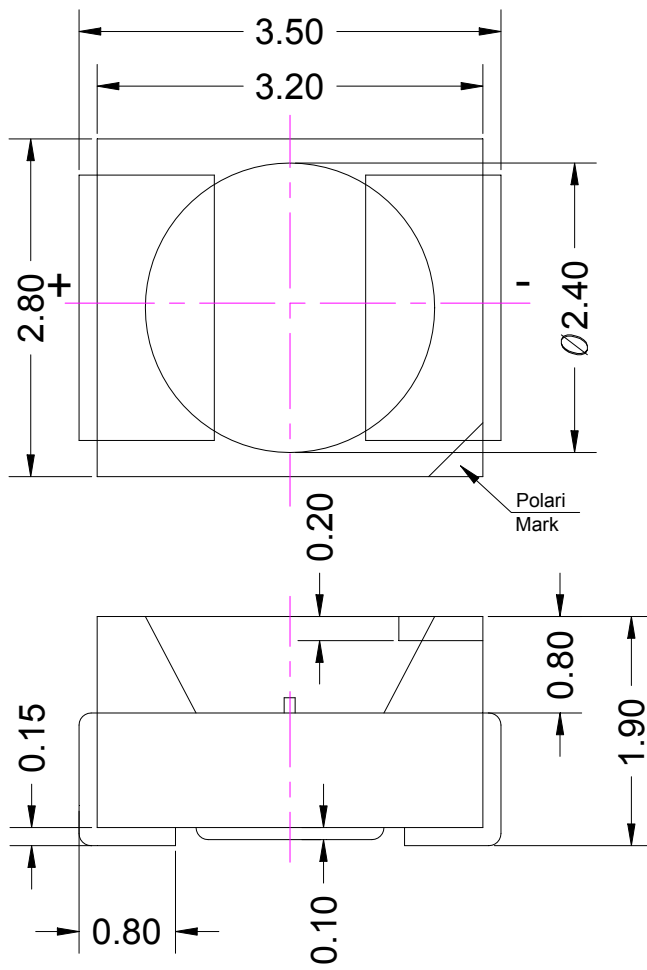




Wen Li	Fang Yang	Jiang Yang	Fang Wang



Tolerance: 0.25(0.01)



Unit mm

Color Pre Green

Lens-color Water clear

Emission Material InGaN

Drawing by Oli a ion



3 Characteristics

Forward current	If	30				mA
Reverse voltage	Vr	5				V
Power dissipation	Pd	110				mW
Operating temperature range	Top	-25 +80				C
Storage temperature range	Tg	-30 +80				C
Peak pulsed current 1/8 d f=1KH	Ifp	125				mA
Wavelength at peak emission	If=20mA	peak	515	520	525	nm
Spectral half bandwidth	If=20mA			10		
Forward voltage	If=20mA	Vf	3.0		3.6	V
Minimum luminous intensity	If=20mA	I	800	1100	1300	mcd



Viewing angle at 50% IV	If=10mA	--	120	--	Deg
Reverse current	Vr=5V	Ir	--	5	A
Useful life	-	IF=20mA	100000		H

Typical Electrical/Optical Characteristics Curve
(Ta=25 Unless Otherwise Noted)

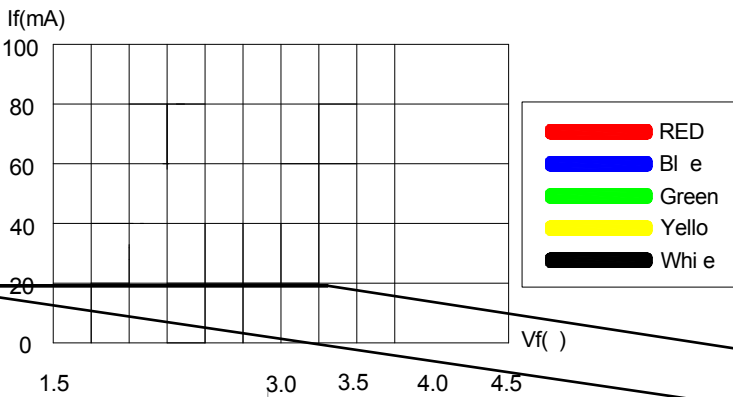


Fig.1 Forward Current vs Forward Voltage

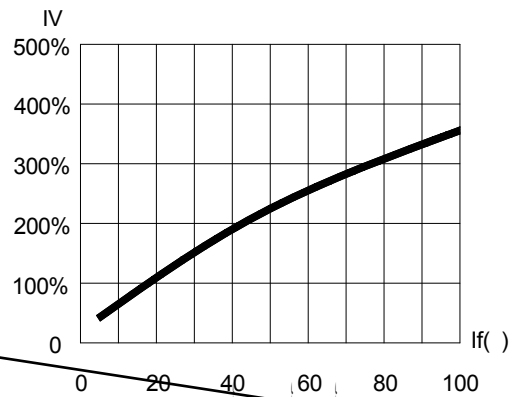


Fig.2 Relative Luminous Intensity vs Forward Voltage

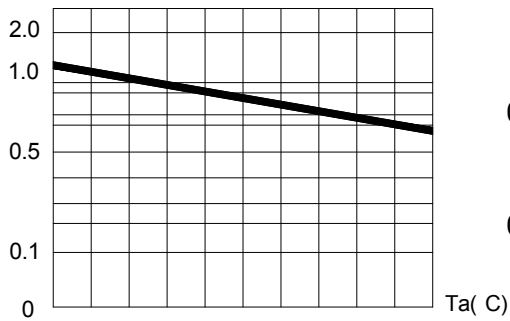


Fig.3 Relative Luminous Intensity vs Ambient Temperature

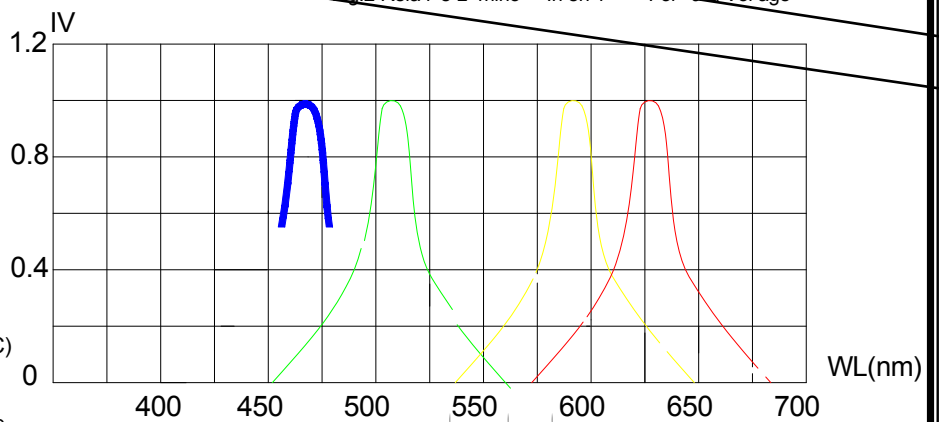


Fig.4 Relative Luminous Intensity vs Wavelength

Directional Characteristics

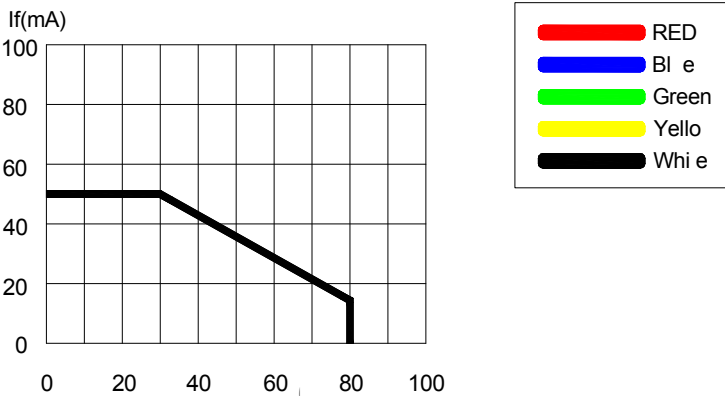
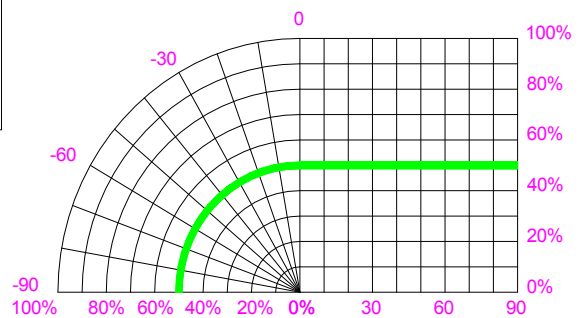


Fig.5 Maximum Forward Current vs Ambient Temperature





1	Tin-plated	Temp 260 ± 5	5 sec.	76 PCS	0/1
2	Back & forth under high & low temp alternating	High temp. +85 30min to 5min to -55 30min	50 bo	76 PCS	0/1
3	Heat shocking	High temp. +100 30min To 10 sec to -10 30min	50 bo	76 PCS	0/1
4	High storage temp.	Temperature 100	1000 Hr.	76 PCS	0/1
5	Low storage temp.	-55	1000 Hr.	76 PCS	0/1
6	Life span	VF=1.9V IF=20mA	1000 Hr.	76 PCS	0/1
7	Test under high temp. & high humidity	85 ± 2/85%RH	1000 Hr.	76 PCS	0/1

i. Iron Soldering: The Iron (max 30W) end temperature less than 300 °C, soldering time 3 seconds, soldering position minimum 2mm from board.

ii. Dip Soldering: Max temperature is 260 °C, time 5s, the position is minimum 2mm from board.

i. Bracket must be bent only if 2mm from colloid.

ii. Bracket mold must be finished by fire or professional.

iii. Bracket mold must be finished before soldering.

i. Bracket mold holder should be connected between the pin, the distance gap of lead and the circuit board.

i. Holder should be paid attention to the ordering of all the devices in case of wrong polarity. Devices can be too close to the heat component, working condition can reduce the limit.

ii. Holder should not assemble LED when the lead are deformed.

iii. When decide to assemble in hole, accurately according to the size of hole and hole distance of the line base

i. Suggest using guard heat positioning

i. Holder should avoid any kind of shake or force on LED, before the soldering temperature return normal.

Holder should be careful. When clean the board with chemical. Some chemical may bring damage to the surface, and bring color fading, such as, Trichloroethylene, Acetone. Should use ethanol or isopropyl alcohol, dip for no more than 3 minutes under the normal temperature.

